

2SK2212

Silicon N Channel MOS FET

REJ03G1003-0200

(Previous: ADE-208-1351)

Rev.2.00 Sep 07, 2005

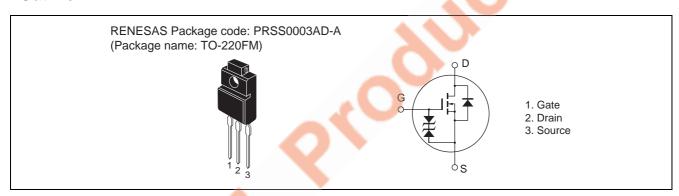
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter, motor control

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	10	А
Drain peak current	I _{D(pulse)} *1	40	А
Body to drain diode reverse drain current	I _{DR}	10	А
Channel dissipation	Pch*2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

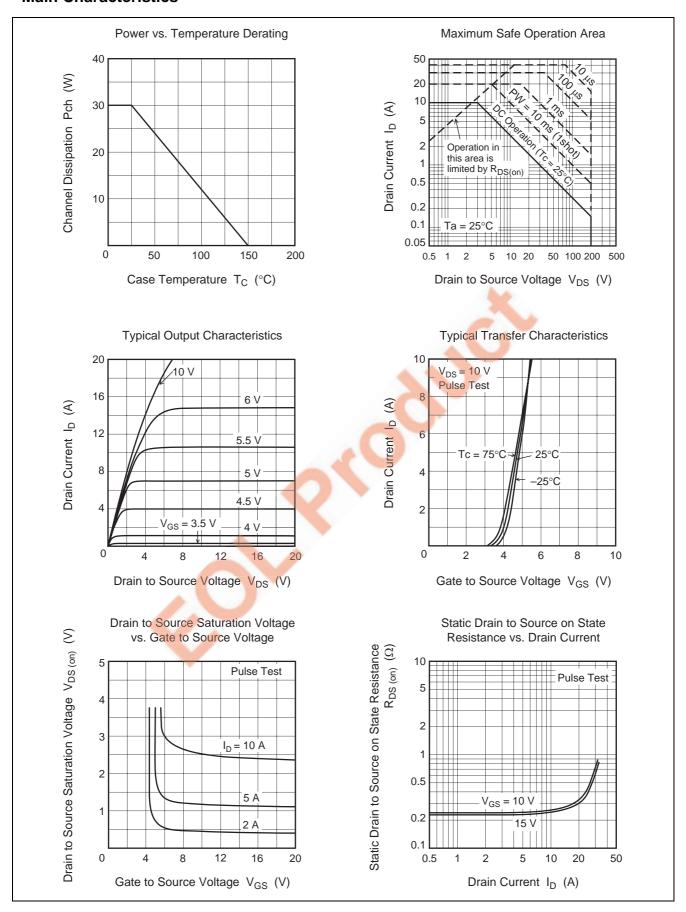
Electrical Characteristics

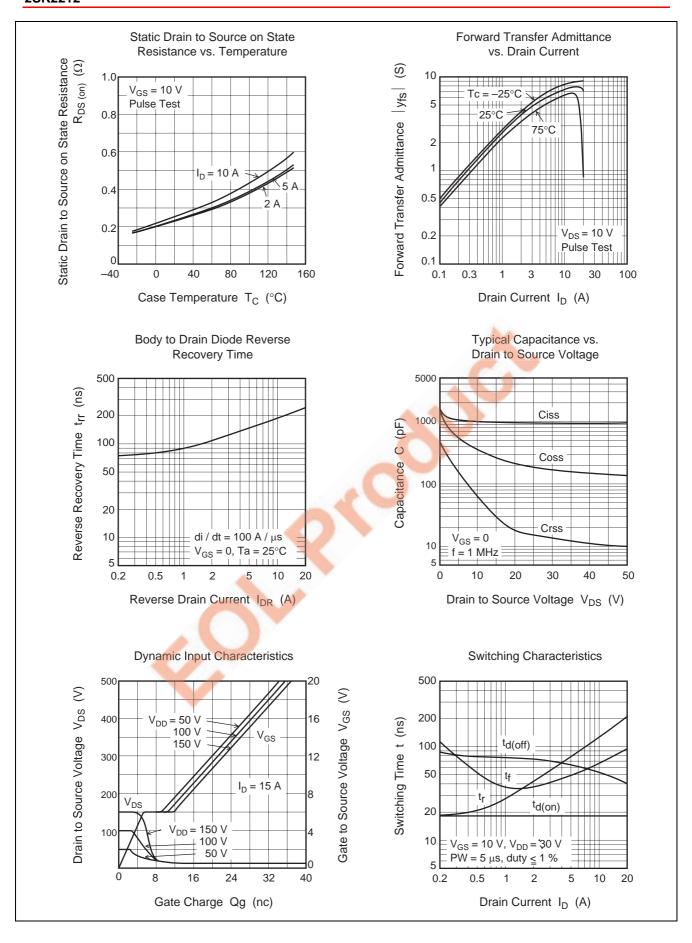
 $(Ta = 25^{\circ}C)$

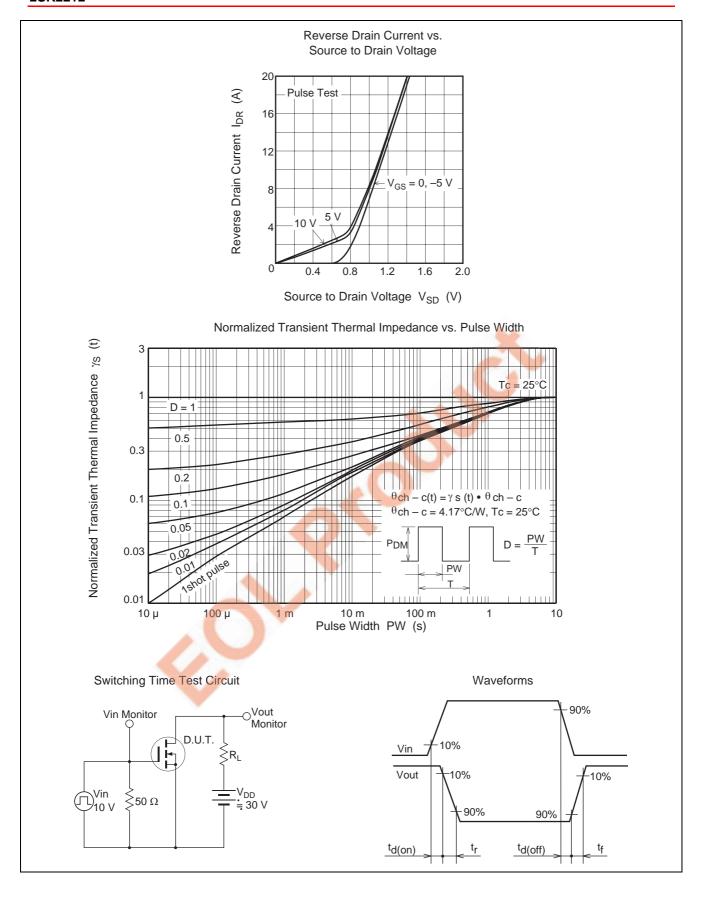
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	200	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	V _{DS} = 160 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	2.0	-/	4.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.24	0.3	Ω	$I_D = 5 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
resistance						
Forward transfer admittance	y _{fs}	3.5	6		S	$I_D = 5 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss		1000	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	F	360	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	7	65	_	pF	1
Turn-on delay time	t _{d(on)}	=	18	_	ns	$I_D = 5 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	-t _n	_	80	_	ns	$R_L = 6 \Omega$
Turn-off delay time	t _{d(off)}	<u> </u>	65	_	ns	
Fall time	t _f	_	50	_	ns	
Body to drain diode forward voltage	V _{DF}	_	1.1	_	V	$I_F = 10 \text{ A}, V_{GS} = 0$
Body to drain diode reverse	t _{rr}	_	190	_	ns	$I_F = 10 \text{ A}, V_{GS} = 0,$
recovery time						di _F / dt = 100 A / μs

Note: 1. Pulse Test

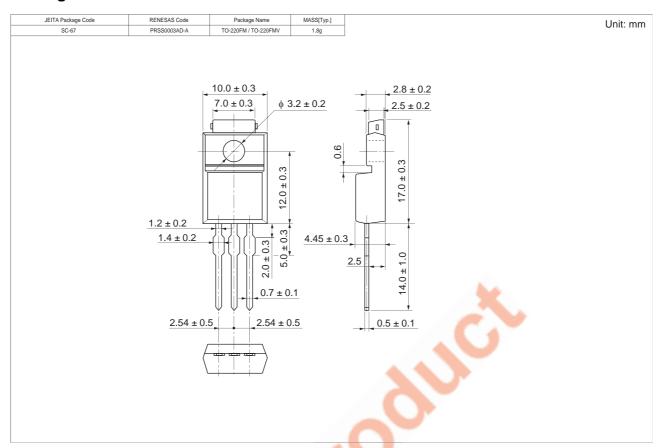
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2212-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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